



Material Content Data Sheet



Sales Product Name		TLE8201R		Issued		28. August 2013		
MA#		MA000694392						
Package		PG-DSO-36-27		Weight*		2054.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.895	0.97	0.97	9686	9686
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		746	
	non noble metal	iron	7439-89-6	30.652	1.49		14923	
	non noble metal	copper	7440-50-8	1244.598	60.59	62.17	605931	621787
wire	noble metal	gold	7440-57-5	9.092	0.44	0.44	4426	4426
encapsulation	organic material	carbon black	1333-86-4	1.435	0.07		698	
	plastics	epoxy resin	-	65.994	3.21		32129	
	inorganic material	silicondioxide	60676-86-0	649.895	31.64	34.92	316401	349228
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7863	7863
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	361	361
solder	noble metal	silver	7440-22-4	0.205	0.01		100	
	non noble metal	tin	7440-31-5	0.137	0.01		66	
	non noble metal	lead	7439-92-1	13.316	0.65	0.67	6483	6649
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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